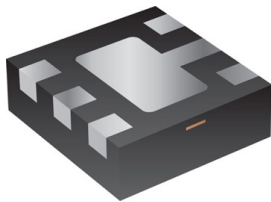


# MATERIAL DECLARATION SHEET



|                 |  |     |   |   |
|-----------------|--|-----|---|---|
| Material Number | ESD Suppressing Device<br>CDDFN6-0504P |     |   |  |
| Product Line    | Semiconductor Products                 |     |   |   |
| Compliance Date | 1 July 2008                            |     |   |   |
| RoHS Compliant  | Yes                                    | MSL | 3 |   |

| No. | Construction Element(subpart) | Homogeneous Material | Material weight [mg] | Homogeneous Material Substances | CASRN if applicable | Materials Mass % | Material Mass % of total unit wt. | Subpart mass of total wt. (%) |
|-----|-------------------------------|----------------------|----------------------|---------------------------------|---------------------|------------------|-----------------------------------|-------------------------------|
| 1   | Wafer                         | Silicon              | 0.12230              | Silicon                         | 7440-21-3           | 100.00%          | 2.459%                            | 2.459%                        |
| 2   | Lead Frame                    | Copper alloy         | 2.67404              | Copper                          | 7440-50-8           | 97.52%           | 53.774%                           | 55.142%                       |
|     |                               |                      | 0.06307              | Iron                            | 7439-89-6           | 2.30%            | 1.268%                            |                               |
|     |                               |                      | 0.00082              | Phosphorus                      | 7723-14-0           | 0.03%            | 0.017%                            |                               |
|     |                               |                      | 0.00411              | Zinc                            | 7440-66-6           | 0.15%            | 0.083%                            |                               |
| 3   | Lead Frame - Ni Plating       | Ni Plating           | 0.02000              | Nickel                          | 7440-02-0           | 100.00%          | 0.402%                            | 0.402%                        |
| 4   | Lead Frame - Pd Plating       | Pd Plating           | 0.02000              | Palladium                       | 7440-05-3           | 100.00%          | 0.402%                            | 0.402%                        |
| 5   | Lead Frame - Au Plating       | Au Plating           | 0.02000              | Gold                            | 7440-57-5           | 100.00%          | 0.402%                            | 0.402%                        |
| 6   | Epoxy                         | Polymer              | 0.00700              | Si-oxide Quartz                 | 14808-60-7          | 42.42%           | 0.141%                            | 0.331%                        |
|     |                               |                      | 0.00450              | Epoxy resin                     | Proprietary         | 27.27%           | 0.090%                            |                               |
|     |                               |                      | 0.00250              | Epoxy resin                     | Proprietary         | 15.15%           | 0.050%                            |                               |
|     |                               |                      | 0.00210              | Epoxy resin modifier            | Proprietary         | 12.73%           | 0.042%                            |                               |
|     |                               |                      | 0.00040              | Aromatic amine                  | Proprietary         | 2.43%            | 0.008%                            |                               |

# MATERIAL DECLARATION SHEET



|                     |               |             |          |                        |              |        |         |         |
|---------------------|---------------|-------------|----------|------------------------|--------------|--------|---------|---------|
| 7                   | Gold Wire     | Noble metal | 0.036296 | Gold                   | 7440-57-5    | 99.99% | 0.7299% | 0.730%  |
|                     |               |             | 0.000004 | Others, not to declare | /            | 0.01%  | 0.0001% |         |
| 8                   | Mold Compound | Polymer     | 0.05990  | Epoxy Resin A          | Trade secret | 3.00%  | 1.205%  | 40.132% |
|                     |               |             | 0.02990  | Epoxy Resin B          | Trade secret | 1.50%  | 0.601%  |         |
|                     |               |             | 0.05990  | Phenol Resin           | Trade secret | 3.00%  | 1.205%  |         |
|                     |               |             | 0.00600  | Carbon Black           | 1333-86-4    | 0.30%  | 0.121%  |         |
|                     |               |             | 1.83990  | Silica Fused           | 60676-86-0   | 92.20% | 37.000% |         |
| <b>Total weight</b> |               |             | 4.97274  |                        |              |        |         |         |

**This Document was updated on: 2015/6/5**

**Important remarks:**

1. It is the responsibility of the user to verify they are accessing the latest version.